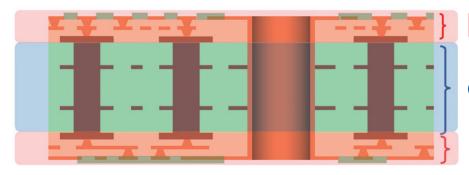
# **TOP LUCINA HS5**

# Additives for acid copper plating for thickness uniformity

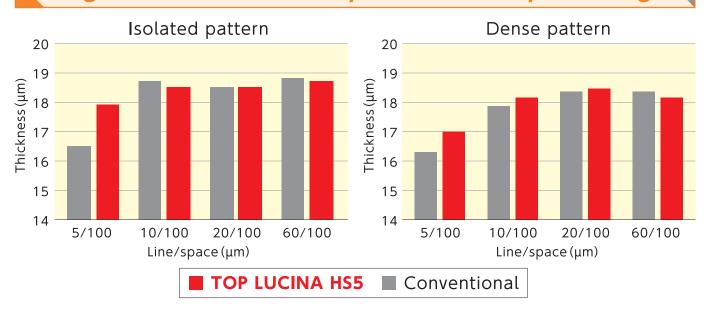
- For pattern plating to build-up layers to achieve thickness uniformity
- Can realize operation at 2 to 3 A/dm² current density
- Control dome-shape occurrence for stacked via



## **Build-up layer**

Core layer

#### High thickness uniformity for ultra-fine patterning



### Control dome-shape occurrence in overfilling

Surface thickness (μm)	4	9	14	18
TOP LUCINA HS5				
Conventional			7	